



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS3035EJ		<b>Issued</b>		19. August 2018		
<b>MA#</b>		MA001472514						
<b>Package</b>		PG-TDSO-8-31		<b>Weight*</b>		67.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.922	2.84	2.84	28425	28425
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		140	
	non noble metal	zinc	7440-66-6	0.038	0.06		562	
	non noble metal	iron	7439-89-6	0.760	1.12		11234	
wire	non noble metal	copper	7440-50-8	30.851	45.63	46.82	456163	468099
	non noble metal	copper	7440-50-8	0.409	0.60	0.60	6044	6044
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.14		1403
plastics	plastics	epoxy resin	-	3.701	5.47		54731	
	inorganic material	silicondioxide	60676-86-0	27.840	41.16	46.77	411648	467782
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7352	7352
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12195	12195
glue	plastics	epoxy resin	-	0.120	0.18		1768	
	noble metal	silver	7440-22-4	0.564	0.83	1.01	8335	10103
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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